

ABSTRACT

ACTUATION MECHANISMS FOR ELECTRICAL INTERCONNECTIONS

Some embodiments described herein include apparatuses and methods of forming such apparatuses. In one such embodiment, an apparatus may include an electronic arrangement, a first die, and a second die coupled to the first die and the electronic arrangement. The electronic arrangement may include an opening. At least a portion of the die may occupy at least a portion of the opening in the electronic arrangement. Other embodiments including additional apparatuses and methods are described.

(Figure No. 2A)